

# **Multilayer Power Inductor**

# CIG10F Series (1608/ EIA 0603)

## APPLICATION

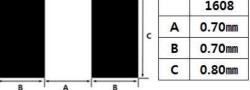
Mobile phones, DSC, DVC, PDA etc. for DC-DC Converter

## **FEATURES**

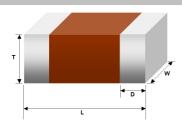
- The smallest multilayer power inductor (1.6mm×0.8mm)
- Much lower Profile than any other series (0.5mm max)
- · Low DC resistance
- · Magnetically shielded structure
- · Free of all RoHS-regulated substances
- · Monolithic structure for high reliability



# 1608



### DIMENSION



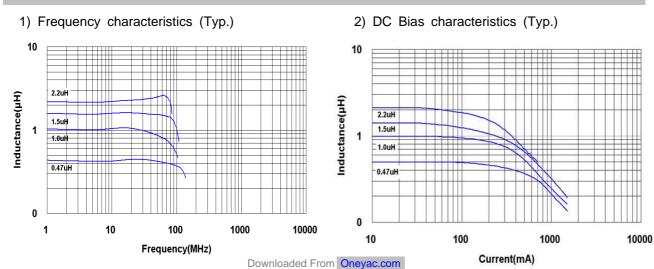
TYPE	Dimension [mm]				
IIFE	L	W	Т	D	
10	1.6±0.15	0.8±0.15	0.5 max.	0.3±0.2	

## **DESCRIPTION**

Dort no	Size	Inductance	DC	Rated Current (A)
Part no.	(inch/mm)	(uH)@1MHz	Resistance(Ω)	Max.
CIG10FR47MNC	0603/1608	0.47±20%	0.20±30 %	0.80
CIG10F1R0MNC	0603/1608	1.0±20%	0.30±30 %	0.70
CIG10F1R5MNC	0603/1608	1.5±20%	0.35±30 %	0.60
CIG10F2R2MNC	0603/1608	2.2±20%	0.45±30 %	0.50

- $\ensuremath{\mathrm{\#}}$  Operating temperature range: –40 to +125°C (Including self-temperature rise)
- \*Test equipment: Agilent :E4991A+16092A

## CHARACTERISTIC DATA





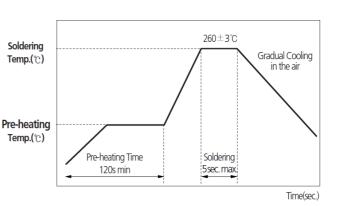
CI	G	10	F	2R2	M	N	С
(1)	(2)	(3)	(4)	(5)	(6)	<b>(7)</b>	(8)

- (1) Chip Inductor
- (3) Dimension
- (5) Inductance (R47:0.47uH, 2R2:2.2uH)
- (7) Thickness option(N:Standard, A:Thinner than standard, B:Thicker than standard) (8) Packaging(C:paper tape, E:embossed tape)
- (2) Power Inductor
- (4) Product Series (F:Low Profile Type)
- (6) Tolerance (M:±20%)

## **REFLOW SOLDERING**

## Soldering 260+0/-5°C 10 sec. max. Temp.(℃) Gradual 260 Cooling 230 in the air 180 150 Soldering Pre-heating 60s max 60~120s 30~60s Time(sec.)

## FLOW SOLDERING



Packaging Style	Quantity(pcs/reel)
Card Board Taping	4,000

■ NOTICE :All specifications are subject to change without previous notice. Please contact with product representatives or engineers to check specifications.

# 单击下面可查看定价,库存,交付和生命周期等信息

>>Samsung Electro-Mechanics(三星电机)